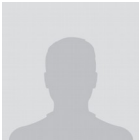


SEMICON® EUROPA

NOV 14-17, 2023 | MUNICH, GERMANY



imec ITF



J.-H. Mohr
Managing Director and Partner
Boston Consulting Group, Munich, Germany



Biography

Coming Soon

The Future of Advanced Packaging Inspection is X-Ray



D. van de Ven
Comet, Hamburg, Germany



Abstract

Key take aways:

- Semiconductor industry is driven by miniaturization & efficiency
- Next generation X-Ray as valuable inspection method for Advanced packaging
- X-Ray as booster for faster time-to-market & increased yield

In Summary:

X-Ray technology is ready as a valuable inspection solution for Advanced Packaging to reduce time-to-market and increase yield.

Biography

Dionys van de Ven
President Industrial X-Ray Systems

Born 1968, Dutch citizen; Master's degree in mechanical engineering from the Eindhoven University of

Technology, Eindhoven

Before joining Comet in 2022, Dionys van de Ven has led Waygate Technologies' x-ray business unit (part of Baker Hughes) as the unit's Business Executive since 2020. In addition, he has been serving as Managing Director of Baker Hughes Digital Solutions GmbH and member of the board of management of GE Inspection Robotics.

Dionys van de Ven began his career at Philips Assembléon in 1997. In 2005 he became Director of Customer Relationship Management at Philips Applied Technologies and, in 2007, Senior Director of Customer Programs, Service and R&D at Philips Healthcare. In 2017, he joined Waygate Technologies.

Topic Coming Soon



J. Behnke
INFICON, Cologne, Germany



Abstract

Coming Soon

Biography

Mr. Behnke has over 35 years of semiconductor industry experience including: logic and memory manufacturing, technology/product development and fab operational excellence. As the GM of Final Phase Systems an INFICON Product Line, John leads a team that develop and deploy SMART software solutions that enable fabs to improve their manufacturing efficiency. FPS's suite of software solutions are built upon a common Datawarehouse which enables advanced Fab Scheduling and optimized WIP movement as well as other related capabilities. He is also a Co-Chair of the Semi North America Smart Manufacturing Special Interest Group.

Prior to FPS John served as the CEO and President of Novati Technologies, the SVP and GM of the Semiconductor Group of Intermolecular, the CVP for Front End Manufacturing, Process R&D and Technology Transfers at Spansion and the Director of AMD's Fab 25's Engineering and Operations groups where he was a founding member of AMD's Automated Precision Manufacturing (APM) initiative which led the Semiconductor industry's development and use of APC and other advanced factory systems. He also led the successful conversion of Fab 25 from Logic to Flash memory which was enabled through the virtual automation of the fab.

Mr. Behnke earned a B.S. degree in Mechanical Engineering with an Industrial Engineering Minor from Marquette University. Mr. Behnke holds five U.S. patents.